



DZ3X062D0L

Silicon epitaxial planar type

For surge absorption circuit

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol:01

■ Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25\text{ }^{\circ}\text{C}$

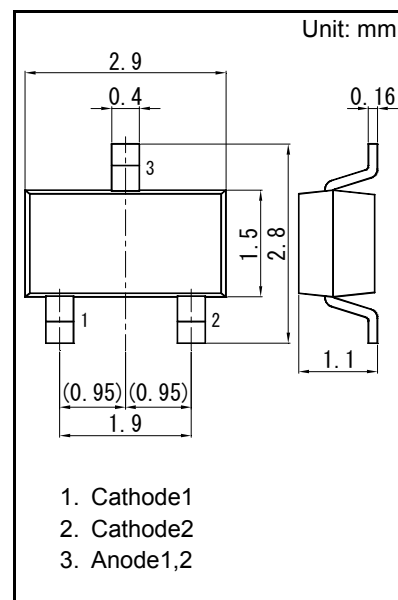
Parameter	Symbol	Rating	Unit
Total power dissipation ^{*1}	PT	200	mW
Electrostatic discharge ^{*2}	ESD	±10	kV
Junction temperature	T_j	150	$^{\circ}\text{C}$
Operating ambient temperature	T_{opr}	-40 to +85	$^{\circ}\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^{\circ}\text{C}$

Note) *1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)

(2 Diode total)

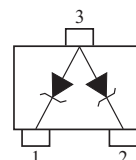
Solder in (1.0 mm x 1.0 mm)

*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω , Contact discharge:10 times)



Panasonic	Mini3-G3-B
JEITA	SC-59A
Code	TO-236AA/SOT-23

Internal Connection



■ Electrical Characteristics $T_a = 25\text{ }^{\circ}\text{C} \pm 3\text{ }^{\circ}\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	$I_F = 10\text{ mA}$			1.0	V
Zener voltage ^{*1, *2}	VZ	$I_Z = 5\text{ mA}$	5.89		6.51	V
Zener operating resistance	RZ	$I_Z = 5\text{ mA}$			50	Ω
Zener rise operating resistance	RZK	$I_Z = 0.5\text{ mA}$			100	Ω
Reverse current	IR	$V_R = 4\text{ V}$			0.2	μA
Temperature coefficient of zener voltage ^{*3}	SZ	$I_Z = 5\text{ mA}$		2.3		mV/ $^{\circ}\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

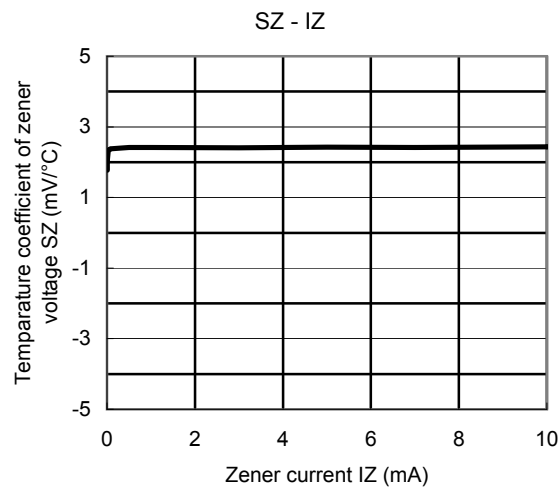
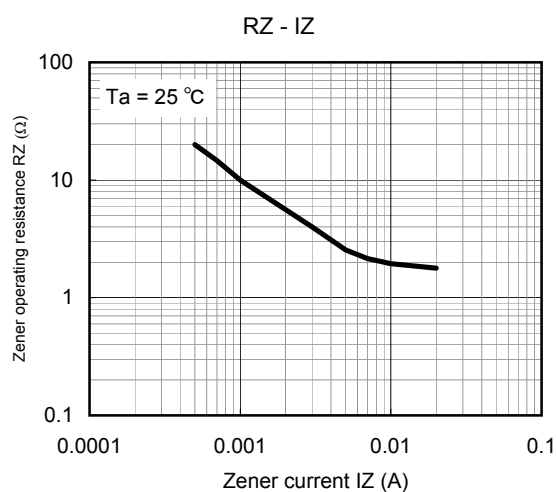
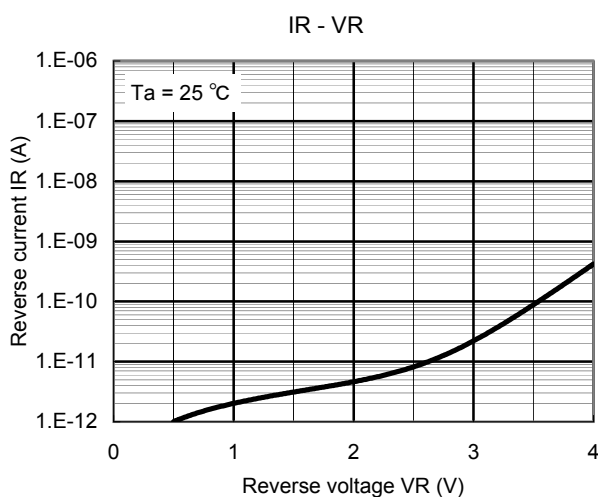
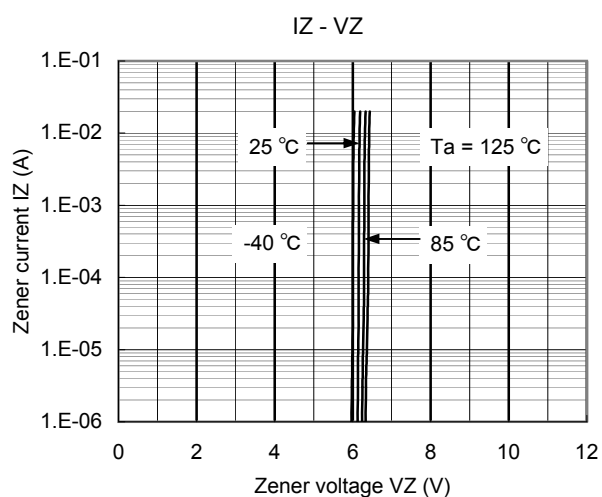
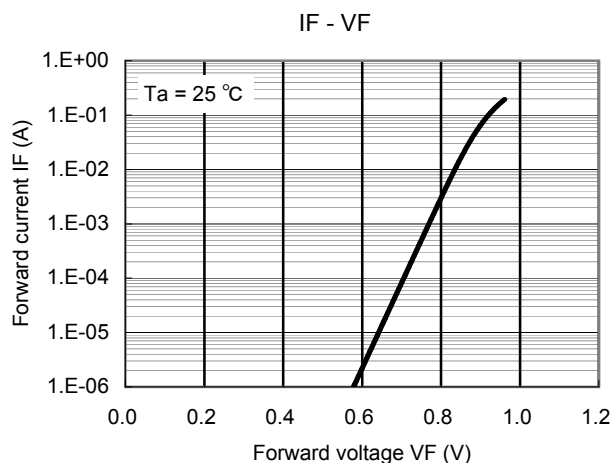
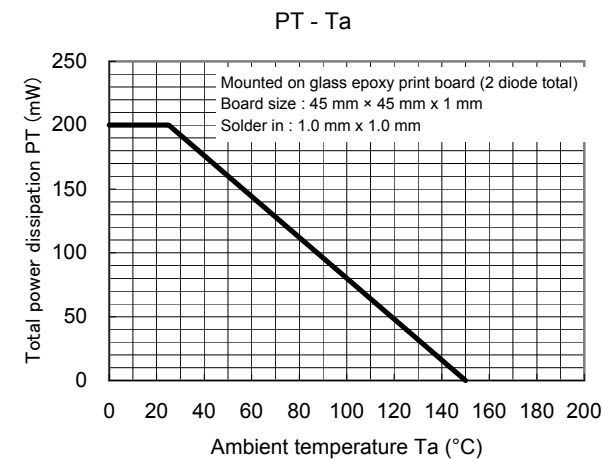
2. *1: The temperature must be controlled $25\text{ }^{\circ}\text{C}$ for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ ($25\text{ }^{\circ}\text{C}$)

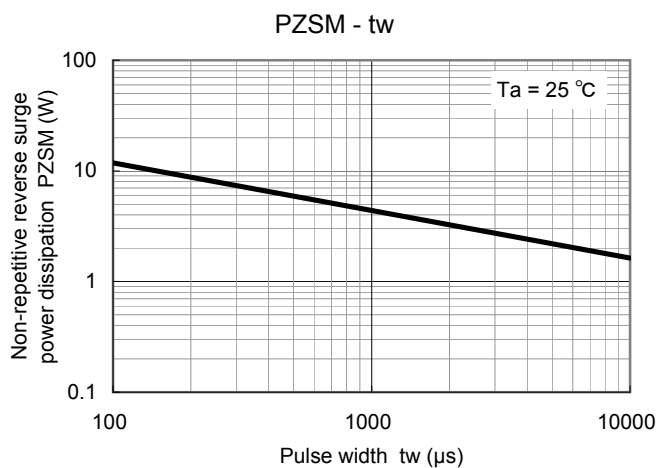
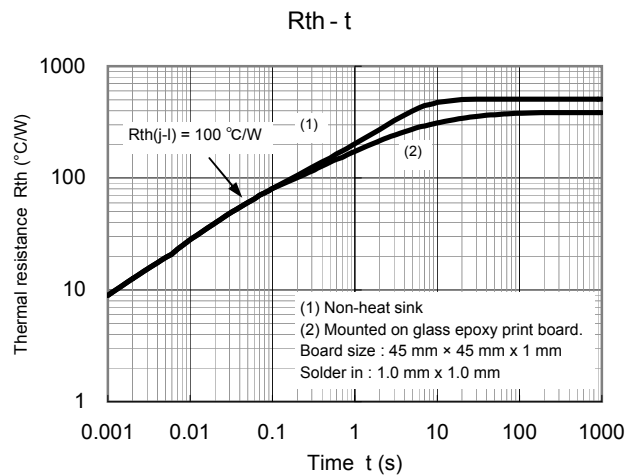
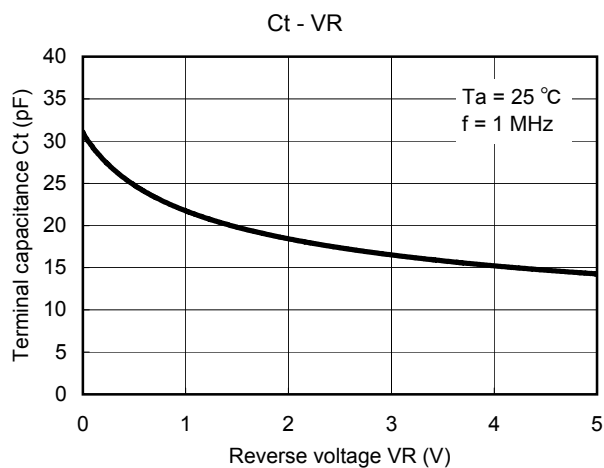
*2: VZ guaranteed 20 ms after current flow.

*3: $T_j = 25\text{ }^{\circ}\text{C}$ to $150\text{ }^{\circ}\text{C}$

Technical Data (reference)



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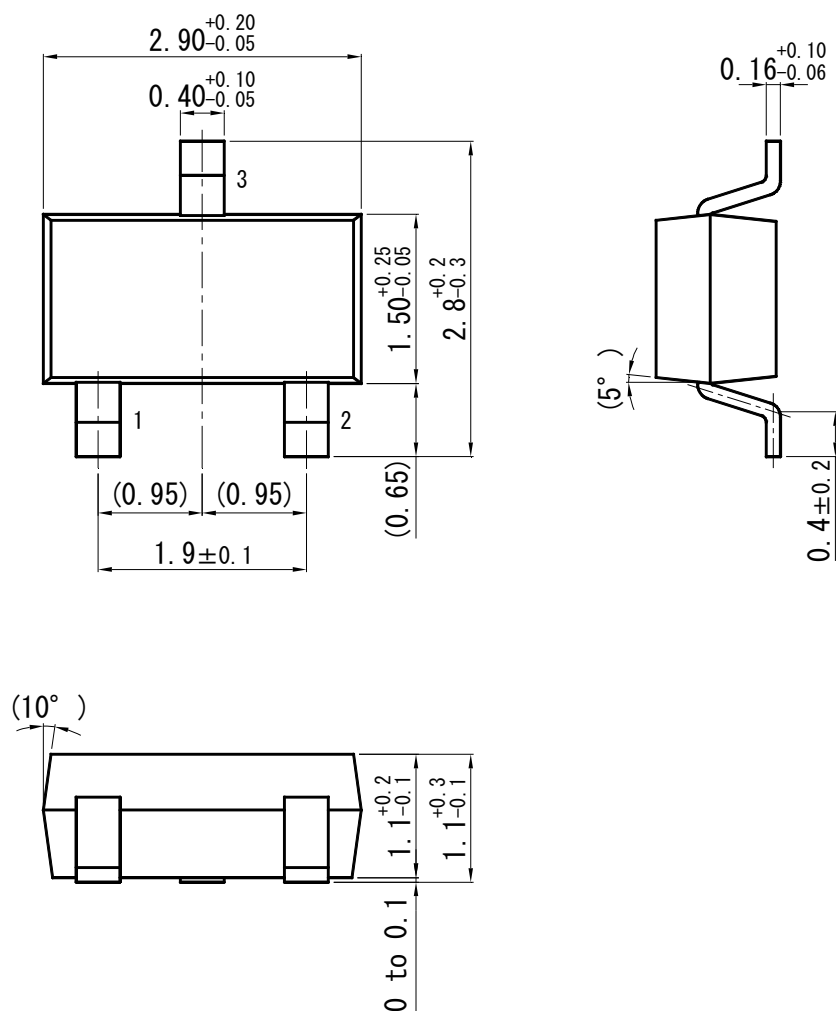


Panasonic

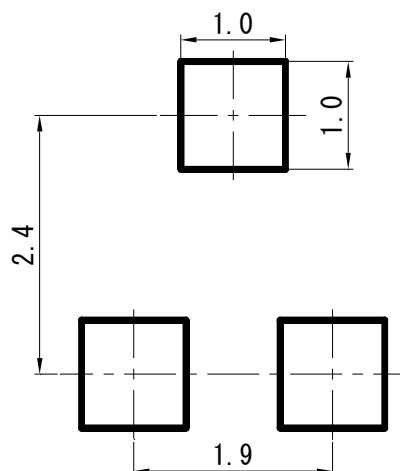
Zener Diode
DZ3X062D0L

Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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